LOGIC DEVICES

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LOGIC Devices announces details of its DDR3 iMOD development

Sunnyvale, CA – LOGIC Devices, Incorporated (NASDAQ: LOGC), a developer of high performance, low power integrated circuits; today announced details of its' DDR3 IMOD product development. LOGIC Devices first DDR3 device is a 4.0 GB, 64 M x 64, DDR3-1333 DRAM available in Industrial (-40˚C - +85˚C), Extended (-40˚C - +105˚C) and Mil temperature (-55˚C - +125˚C) grades, and packaged in a 16mm x 22mm, thermally enhanced, 271ball -1.00mm pitch, PBGA. This devices provides a 40% space savings over the use of (4) 96 ball, 9.00+mm x 16.00+mm BGAs as well as a 30% decrease in total I/O, all while providing major improvements in heat dissipation via use of proprietary packaging IP. Other targeted performance benchmarks include DDR3-1066 at extended temperature (-40C - + 105C) and DDR3-800 at military temperature (-55C - +125C). LOGIC Devices 16mm x 22mm, thermally enhanced, 271 ball package, will facilitate space savings while improving the routing of the customers parent Printed Wire Board (PWB). The Signal/ball definition facilitates the DDR3 requirements while allowing for backwards compatibility DDR2 in a similar or equal mechanical footprint with a 208 signal/ball electrical interface. LOGIC Devices signal/ball matrix definition and mechanical diagram are included directly below.

	1	2	3	4	5	6	7	8	9	10	11	12	13	
A		VssQ	VccQ	VccQ	NC	NC	VssQ	NC	NC	VccQ	VccQ	VssQ	VssQ	A
B	VssQ		Vcc	Vss	Vcc	Vcc	Vss	Vcc	Vcc	Vss	Vcc	Vss	VssQ	B
C	VccQ	Vcc	Vss	NC	ZQ3	ZQ2	NC	NC	NC	NC	Vss	Vcc	VccQ	C
D	VccQ	Vss	NC	NC	ZQ0	ZQ1	NC	NC	DQ34	CK3	CK3\	Vss	VccQ	D
E	NC	DQ35	DQ51	NC	NC	RESET\	VrefCA	DQ50	DQ53	DQ37	CK2\	CK2	NC	E
F	NC	DQ52	DQ36	DQ33	NC	BA2	RFU	DQ39	LDQS2	LDQS3	DQ48	DQ32	NC	F
G	NC	LDM3	LDM2	DQ49	DQ43	DQ59	RFU	DQ55	DQ58	DQ42	LDQS2\	LDQS3\	NC	G
H	NC	DQ38	DQ54	DQ60	DQ57	UDM2	Vss	DQ63	DQ56	DQ40	DQ61	DQ45	NC	H
J	NC	UDM3	DQ44	DQ41	DQ46	DQ62	Vcc	UDQS2\	DQ47	UDQS2	UDQS3	UDQS3\	NC	J
K	VccQ	Vcc	A6	A10	A9	Vcc	Vss	Vcc	A3	A12	RFU	Vcc	VccQ	K
L	VssQ	Vss	A0	A11	Vcc	Vss	VrefDA	Vss	Vcc	A1	BA1	Vss	VssQ	L
M	VccQ	Vcc	A2	A4	A8	Vcc	Vss	Vcc	BA0	A5	A7	Vcc	VccQ	M
N	NC	UDQS1\	UDQS1	UDQS0	DQ15	UDQS0\	Vcc	DQ30	DQ14	DQ9	DQ12	UDM1	NC	N
P	NC	DQ13	DQ29	DQ8	DQ24	DQ31	Vss	UDM0	DQ25	DQ28	DQ22	DQ6	NC	P
R	NC	LDQS1\	LDQS0\	DQ10	DQ26	DQ23	ODT	DQ27	DQ11	DQ17	LDM0	LDM1	NC	R
T	NC	DQ0	DQ16	LDQS1	LDQS0	DQ7	NC	NC	NC	DQ1	DQ4	DQ20	NC	T
U	NC	CK0	CK0\	DQ5	DQ21	DQ18	NC	NC	CKE	WE\	DQ19	DQ3	NC	U
V	VccQ	Vss	CK1\	CK1	DQ2	RAS\	CAS\	NC	NC	NC	NC	Vss	VccQ	V
W	VccQ	Vcc	Vss	NC	NC	CS\	NC	NC	NC	NC	Vss	Vcc	VccQ	W
Y	VssQ	Vss	Vcc	Vss	Vcc	Vcc	Vss	Vcc	Vcc	Vss	Vcc	Vss	VssQ	Y
AA	VssQ	VssQ	VccQ	VccQ	NC	NC	VssQ	NC	NC	VccQ	VccQ	VssQ	VssQ	AA
	1	2	3	4	5	6	7	8	9	10	11	12	13	

GND (Core) | V+ (Core Power) | UNPOPULATED | Address
GND (I/O) | V+ (I/O Power) | NC
Data I/O | CNTRL | Level/Current REF.

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OPTIONS	Monolithic Solution	IMOD Solution	SAVINGS
	DDR3 9.0mm x 15.5mm 96 ball FBGA; DDR3 9.0mm x 15.5mm 96 ball FBGA; DDR3 9.0mm x 15.5mm 96 ball FBGA; DDR3 9.0mm x 15.5mm 96 ball FBGA	LOGIC DEVICES; LDI Part No.; 22.0; 16.0	
Area	4 x 139.5mm^2 = 558mm2 PLUS	352mm^2	~40%
I/O	4 x 96 pins = 384 pins total	271 Balls/Locations	30%

The IMOD family is based on integration of multiple silicon devices, manufactured on an organic laminate substrate and encapsulated with industry standard plastic encapsulating materials providing suitability of use in Industrial, Extended and Mil-Temp applications. LOGIC Devices DDR3, thermally enhanced IMOD package adds, via packaging IP, a method for greatly improving the thermal conductivity via providing a low resistance thermal path to the package topside, in addition to the thermal properties normally associated with BGA packaging. This packaging technology now promotes excellent thermal relief via the bottom side interface, as well as adding a vastly improved thermal path via the topside package surface. This integrated product family provides a medium which offers customers significant board area savings, improved electrical characteristics such as lower capacitance, lower inductance, controlled impedance and excellent thermal properties, while minimizing manufacturing issues related to ultra fine pitch ball matrixes and trace routeability issues encountered with discrete component based solutions.

LOGIC Devices' leadership DDR3 product, scheduled to begin sampling in Q2-09, with production shipments schedule to commence in Q3-09 will have initial Industrial target price of $189.00(25-49) for the DDR3-1333, $175.00 for the DDR3-1066 and $168.00 for our DDR3-800 device offerings. Target pricing for our extended temperature devices are $214.00(25-49pcs) for the DDR3-1066, and $205.00 for our DDR3-800 device. Target price for our Mil-Temp DDR3-800 is $264.00(25-49pcs).

LOGIC Devices Incorporated (NASDAQ: LOGC) an ISO9001:2000 registered corporation, is focused on developing high performance digital silicon and integrated product solutions for high performance, power sensitive applications. Our products meet or exceed the requirements for broadcast video, medical imaging, industrial-embedded computer, surveillance, and instrumentation as well as telecommunications companies. More information about LOGIC Devices and its' products is available at www.logicdevices.com.

"Safe Harbor" Statement under the Private Securities Litigation Reform Act of 1995: Any statements in this press release regarding expectations of future events are "forward-looking statements" involving risks and uncertainties, including, but not limited to, market acceptance risks, the effect of economic conditions and shifts in supply and demand, the impact of competitive products and pricing, product development, commercialization and technological difficulties, availability of capital, and capacity and supply constraints. Please refer to the Management Discussion and Analysis of Financial Condition and Results of Operations (MD&A) for a discussion of risks in the most recent LOGIC Devices Annual Report on Form 10-K and the quarterly report under Form 10-Q.

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